



cket No. 0756-2011

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)
Shunpei YAMAZAKI et al.)
Serial No. 09/362,192)
Filed: July 28, 1999) Group Art Unit: 2815
For: SEMICONDUCTOR DEVICE) Examiner: D. Hardy
HAVING SEMICONDUCTOR)
CIRCUIT COMPRISING)
SEMICONDUCTOR ELEMENT)
AND METHOD FOR)
MANUFACTURING THE SAME)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with
The United States Postal Service with sufficient postage as First
Class Mail in an envelope addressed to: Assistant Commissioner
for Patents, Washington, D.C. 20131, on 2/27/01

AMENDMENT AND RESPONSE TO ELECTION REQUIREMENT

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action of September 21, 2000, please amend the subject
application as follows:

IN THE CLAIMS:

Cancel claims 1-28 without prejudice to applicants' right to file a division application
with respect thereto.

[Please add new claims 45-59:]

45. A method for manufacturing a semiconductor device comprising steps of:
forming an initial semiconductor film formed over a substrate;
subjecting said semiconductor film to oxygen plasma; and

02/20/2001 WPM11 00000072-09362192

01 FC:116
02 FC:102

590.00 AD
160.00 AD

NVA170799.1

02/20/2001 WPM11 00000072-09362192